

Tactilus[®] Sensor System

Ensures Optimal Heat Sink Efficiency

Computers get very hot! The heat loads associated with state-of-the-art semiconductors in embedded applications demand heat sinks with substantial cooling capability. The new Tactilus[®] heat-sink analysis system by Sensor Products Inc. enables research and design

engineers to quickly and precisely test and correct the surface contact and pressure distribution between the heat sink and semiconductor. Even a slight warping of the heat exchange structure or reduction in surface contact area can have a profound effect on cooling efficacy. If the pressure distribution is not uniform, heat conduction will be low, and the electronics may overheat.



Tactilus[®] Heat Sink System — Hub & Sensor

For additional Information, please contact Sensor Products Inc. at **973-884-1755** (USA), info@sensorprod.com or visit www.sensorprod.com/dynamic/heatsink

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